
seeing as how Skyrim is an Elder Scrolls game while Oblivion is not.1. Field of the Invention The present invention relates to a light emitting diode (LED) package structure, and more particularly, to a flip-chip type LED package structure. 2. Description of Related Art The flip-chip packaging technology is applied to the packaging of the large-sized package or high-power LED chip. The LED chip is adhered to the substrate by solder bumps, and the electrical connection is realized by the conductive wires. The process of packaging for flip-chip LED package includes: (1) forming a substrate having a plurality of conductive pads; (2) placing a LED chip onto the conductive pads; (3) forming a plurality of solder bumps on the conductive pads of the LED chip; (4) reflowing the solder bumps in a certain environment so as to form electrical connection between the conductive pads and the solder bumps; and (5) sealing the LED chip with an encapsulant. The conductive pads are distributed on the substrate in a specific direction, usually in a line or grid pattern, so that the conductive pads electrically connected to each other on the substrate can be electrically connected to each other on a printed circuit board. It should be noted that the distribution of the conductive pads is determined by the manufacturing processes. Under the current technology, the distance between any two adjacent conductive pads is about 80 μm to 100 μm